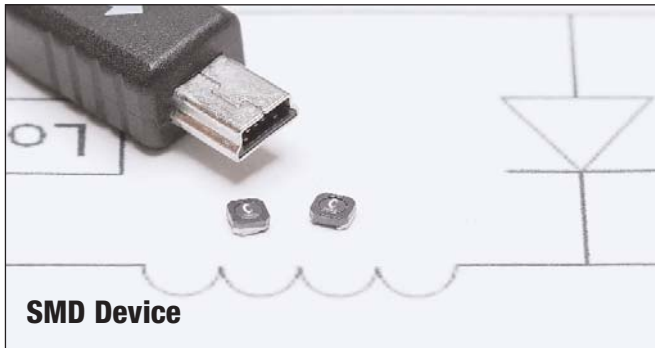


# Low Profile, High Power, Shielded Drum Inductors

## SDH2812 Series



**SMD Device**

### Description

- Halogen Free
- 125°C maximum total temperature operation
- 3.2 x 3.0 x 1.2mm maximum shielded drum core
- Ferrite core material
- High power density, ultra-compact footprint
- Inductance range from 1.02μH to 97.7μH
- Current range from 0.217 to 1.95 Amps
- Magnetically shielded, low EMI
- RoHS compliant

### Applications

- Buck or boost inductor
- Cellular phones/ PDAs
- LED Photo flash
- LCD Displays
- Handheld/Mobile devices
- GPS Systems
- Digital cameras
- MP3 Players

### Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

### Packaging

- Supplied in tape and reel packaging, 4,500 parts per reel 13" diameter reel

### Product Specifications

Part Number <sup>5</sup>	OCL <sup>1</sup> (μH)	Part Marking Designator	I <sub>rms</sub> <sup>2</sup> (Amps)	I <sub>sat</sub> <sup>3</sup> @ 25°C (Amps)	DCR (Ω) @ 20°C (Typical)	DCR (Ω) @ 20°C (Maximum)	K-factor <sup>4</sup>
SDH2812-1R0-R	1.02±30%	O	1.45	1.95	0.062	0.083	1212
SDH2812-1R5-R	1.50±30%	A	1.33	1.71	0.082	0.102	1070
SDH2812-2R2-R	2.20±20%	B	1.26	1.53	0.095	0.114	866
SDH2812-3R3-R	3.20±20%	C	1.08	1.16	0.138	0.154	673
SDH2812-4R7-R	4.20±20%	D	0.900	1.000	0.200	0.224	587
SDH2812-6R8-R	6.60±20%	E	0.730	0.830	0.270	0.336	466
SDH2812-8R2-R	8.17±20%	F	0.660	0.780	0.380	0.417	404
SDH2812-100-R	9.67±20%	G	0.620	0.710	0.389	0.467	387
SDH2812-150-R	14.7±20%	H	0.500	0.570	0.620	0.721	308
SDH2812-220-R	21.6±20%	I	0.440	0.460	0.870	0.922	264
SDH2812-330-R	33.2±20%	J	0.350	0.380	1.37	1.43	209
SDH2812-470-R	46.7±20%	K	0.300	0.320	1.72	1.99	173
SDH2812-680-R	68.0±20%	L	0.270	0.270	2.46	2.70	148
SDH2812-820-R	82.2±20%	M	0.230	0.240	3.15	3.47	135
SDH2812-101-R	97.7±20%	N	0.217	0.218	3.61	3.97	122

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0Adc

2 I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

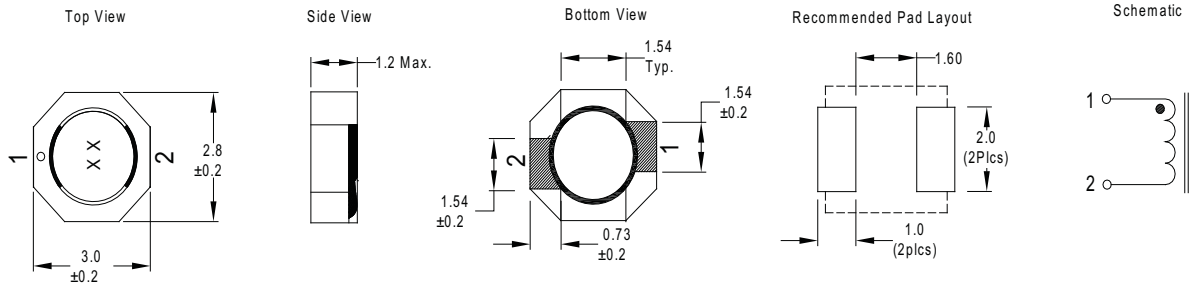
3 I<sub>sat</sub>: Peak current for approximately 30% rolloff at +25°C.

4 K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K \* L \* ΔI. B<sub>p-p</sub> (Gauss), K: (K-factor from table), L: (inductance in μH), ΔI (peak-to-peak ripple current in amps).

5 Part Number Definition: SDH2812-xxx-R

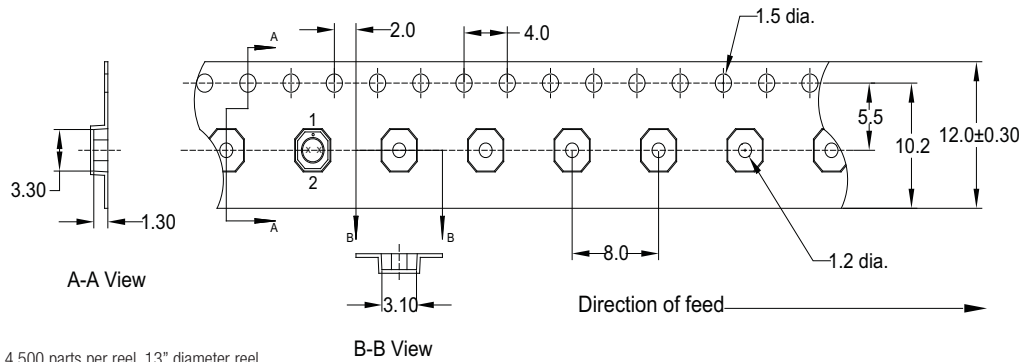
- SDH2812 = Product code and size
- xxx= Inductance value in μH, R = decimal point, If no R is present then 3<sup>rd</sup> digit equals number of zeros.
- "-R" suffix = RoHS compliant

### Dimensions - mm



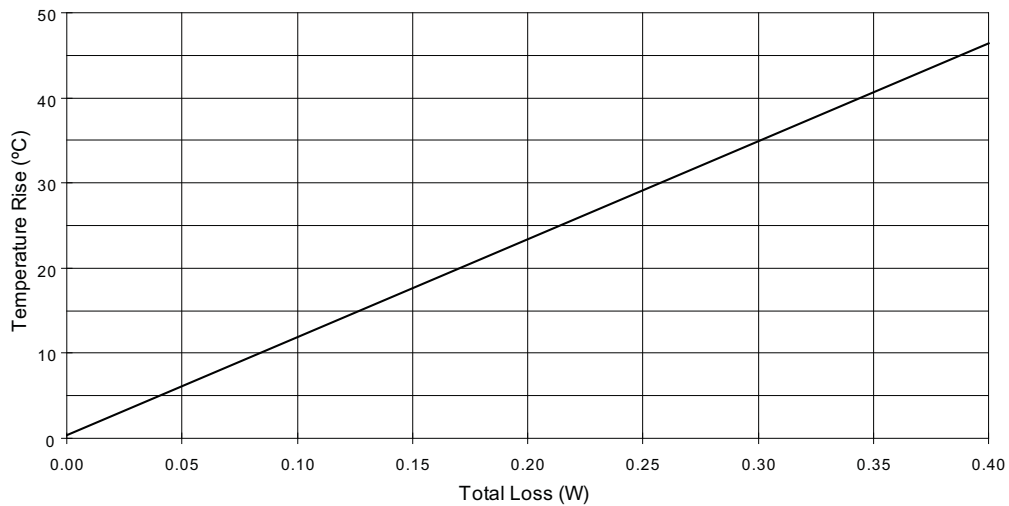
Two-digit (2) Part Marking:  
 1<sup>st</sup> Digit indicates inductance value per "Part Marking Designator" column in Product Specifications table  
 2<sup>nd</sup> Digit indicates bi-weekly production date code

### Packaging Information - mm

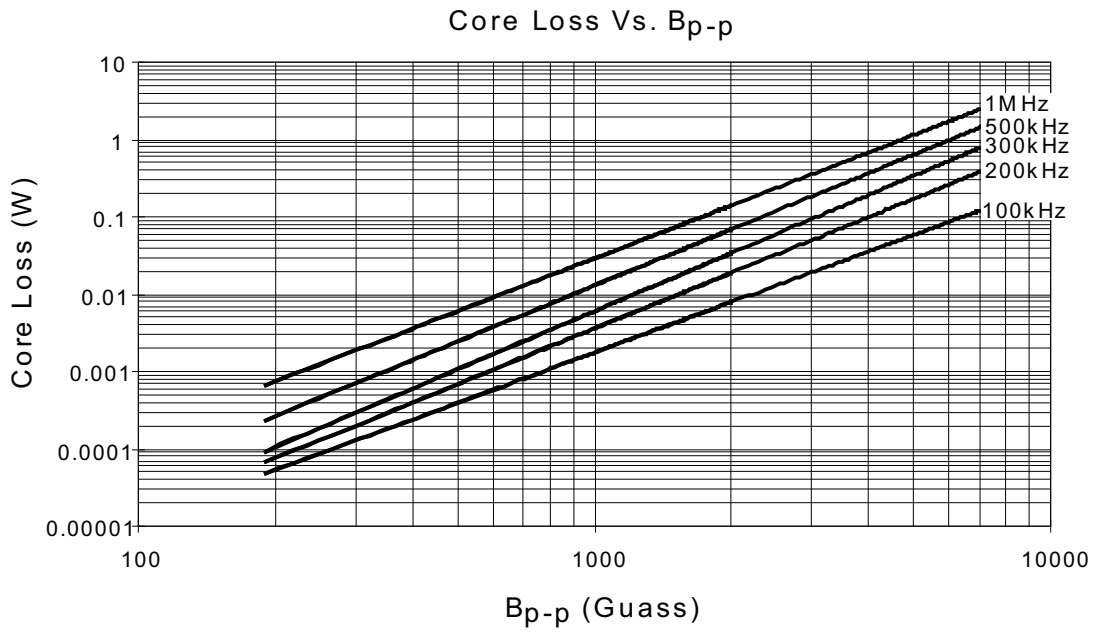


Supplied in tape-and-reel packaging, 4,500 parts per reel, 13" diameter reel.

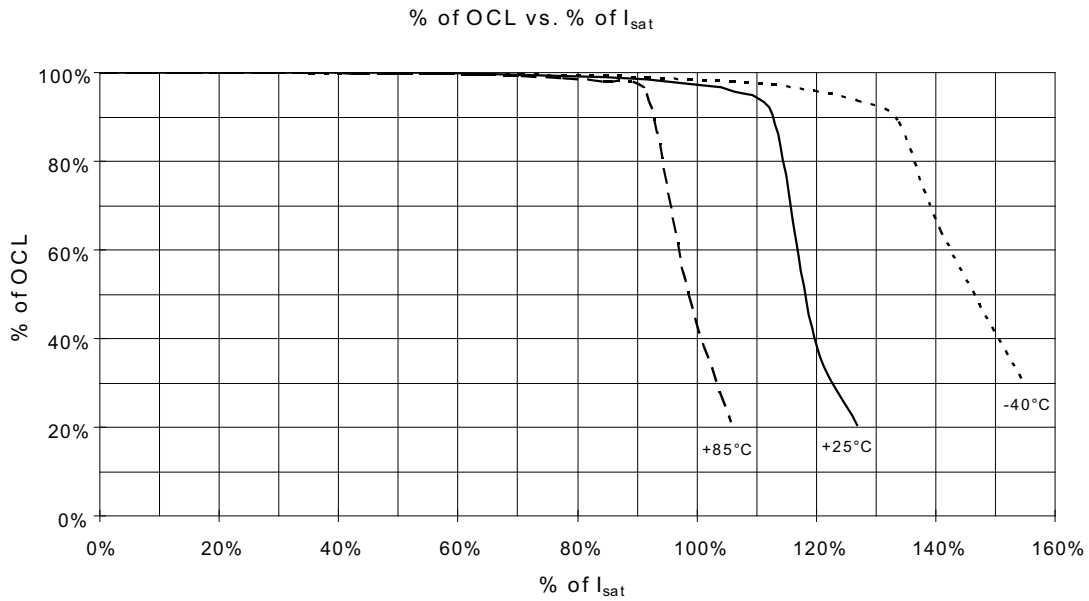
### Temperature Rise vs. Total Loss



## Core Loss



## Inductance Characteristics



## Solder Reflow Profile

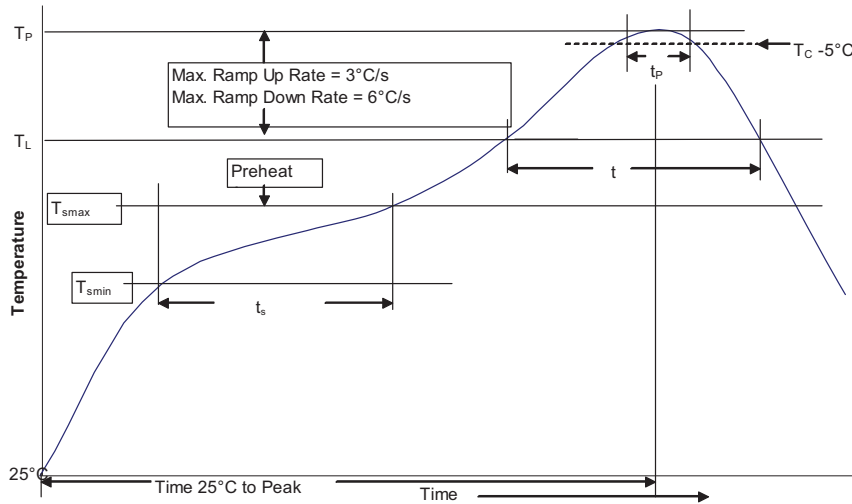


Table 1 - Standard SnPb Solder ( $T_C$ )

Package Thickness	Volume $mm^3$ <350	Volume $mm^3$ $\geq 350$
<2.5mm	235°C	220°C
$\geq 2.5mm$	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_C$ )

Package Thickness	Volume $mm^3$ <350	Volume $mm^3$ 350 - 2000	Volume $mm^3$ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_P$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_P$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_C$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_P$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

### North America

Cooper Electronic Technologies  
1225 Broken Sound Parkway NW  
Suite F  
Boca Raton, FL 33487-3533  
Tel: 1-561-998-4100  
Fax: 1-561-241-6640  
Toll Free: 1-888-414-2645

Cooper Bussmann  
P.O. Box 14460  
St. Louis, MO 63178-4460  
Tel: 1-636-394-2877  
Fax: 1-636-527-1607

### Europe

Cooper Electronic Technologies  
Cooper (UK) Limited  
Burton-on-the-Wolds  
Leicestershire • LE12 5TH UK  
Tel: +44 (0) 1509 882 737  
Fax: +44 (0) 1509 882 786

Cooper Electronic Technologies  
Avda. Santa Eulalia, 290  
08223  
Terrassa, (Barcelona), Spain  
Tel: +34 937 362 812  
+34 937 362 813  
Fax: +34 937 362 719

### Asia Pacific

Cooper Electronic Technologies  
1 Jalan Kilang Timor  
#06-01 Pacific Tech Centre  
Singapore 159303  
Tel: +65 278 6151  
Fax: +65 270 4160

The only controlled copy of this Data Sheet is the electronic read-only version located on the Cooper Bussmann Network Drive. All other copies of this document are by definition uncontrolled. This bulletin is intended to clearly present comprehensive product data and provide technical information that will help the end user with design applications. Cooper Bussmann reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Cooper Bussmann also reserves the right to change or update, without notice, any technical information contained in this bulletin. Once a product has been selected, it should be tested by the user in all possible applications.

Life Support Policy: Cooper Bussmann does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.